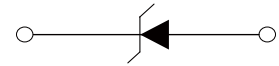


FEATURES

- Planar Die construction
- 500mW Power Dissipation
- Ideally Suited for Automated Assembly Processes



DO-35



Schematic Symbol

MECHANICAL DATA

- Case: Molded Glass DO-35
- Terminals: Solderable per MIL-STD-750, Method 2026
- Mounting position: Any

APPROVALS

- RoHS** Compliance with 2011/65/EU
- HF** Compliance with IEC61249-2-21:2003

MAXIMUM RATINGS ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Value	Unit
Power dissipation at $T_A = 25^{\circ}\text{C}$	P_{TOT}	500	mW
Forward voltage at $I_F=200\text{mA}$	V_F	1.1	V
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	0.3*	$^{\circ}\text{C}/\text{mW}$
Junction temperature range	T_J	175	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-65 to +175	$^{\circ}\text{C}$

*Valid provided that leads at a distance of 10 mm from case are kept at ambient temperature.

ELECTRICAL CHARACTERISTICS

Part Number	Device Marking Code	Nominal Zener Voltage			Max. Zener Impedance				Maximum Reverse Leakage Current	
		$V_Z @ I_{ZT}$			$Z_{ZT} @ I_{ZT}$		$Z_{ZK} @ I_{ZK}$		$I_R @ V_R$	
		Nom.(V)	Min.(V)	Max.(V)	Ω	mA	Ω	mA	μA	V
1N5221B	1N5221B	2.4	2.28	2.52	30	20	1200	0.25	100	1
1N5222B	1N5222B	2.5	2.38	2.63	30	20	1250	0.25	100	1
1N5223B	1N5223B	2.7	2.57	2.84	30	20	1300	0.25	75	1
1N5224B	1N5224B	2.8	2.66	2.94	30	20	1400	0.25	75	1
1N5225B	1N5225B	3	2.85	3.15	29	20	1600	0.25	50	1
1N5226B	1N5226B	3.3	3.14	3.47	28	20	1600	0.25	25	1
1N5227B	1N5227B	3.6	3.42	3.78	24	20	1700	0.25	15	1
1N5228B	1N5228B	3.9	3.71	4.1	23	20	1900	0.25	10	1
1N5229B	1N5229B	4.3	4.09	4.52	22	20	2000	0.25	5	1
1N5230B	1N5230B	4.7	4.47	4.94	19	20	1900	0.25	5	2
1N5231B	1N5231B	5.1	4.85	5.36	17	20	1600	0.25	5	2
1N5232B	1N5232B	5.6	5.32	5.88	11	20	1600	0.25	5	3
1N5233B	1N5233B	6.0	5.7	6.3	7	20	1600	0.25	5	3.5
1N5234B	1N5234B	6.2	5.89	6.51	7	20	1000	0.25	5	4
1N5235B	1N5235B	6.8	6.46	7.14	5	20	750	0.25	3	5
1N5236B	1N5236B	7.5	7.13	7.88	6	20	500	0.25	3	6
1N5237B	1N5237B	8.2	7.79	8.61	8	20	500	0.25	3	6.5
1N5238B	1N5238B	8.7	8.27	9.14	8	20	600	0.25	3	6.5
1N5239B	1N5239B	9.1	8.65	9.56	10	20	600	0.25	3	7
1N5240B	1N5240B	10	9.5	10.5	17	20	600	0.25	3	8
1N5241B	1N5241B	11	10.45	11.55	22	20	600	0.25	2	8.4
1N5242B	1N5242B	12	11.4	12.6	30	20	600	0.25	1	9.1
1N5243B	1N5243B	13	12.35	13.65	13	9.5	600	0.25	0.5	9.9
1N5244B	1N5244B	14	13.3	14.7	15	9	600	0.25	0.1	10
1N5245B	1N5245B	15	14.25	15.75	16	8.5	600	0.25	0.1	11
1N5246B	1N5246B	16	15.2	16.8	17	7.8	600	0.25	0.1	12
1N5247B	1N5247B	17	16.15	17.85	19	7.4	600	0.25	0.1	13
1N5248B	1N5248B	18	17.1	18.9	21	7	600	0.25	0.1	14
1N5249B	1N5249B	19	18.05	19.95	23	6.6	600	0.25	0.1	14
1N5250B	1N5250B	20	19	21	25	6.2	600	0.25	0.1	15
1N5251B	1N5251B	22	20.9	23.1	29	5.6	600	0.25	0.1	17
1N5252B	1N5252B	24	22.8	25.2	33	5.2	600	0.25	0.1	18
1N5253B	1N5253B	25	23.75	26.25	35	5	600	0.25	0.1	19

Part Number	Device Marking Code	Nominal Zener Voltage			Max. Zener Impedance				Maximum Reverse Leakage Current	
		$V_Z @ I_{ZT}$			$Z_{ZT} @ I_{ZT}$		$Z_{ZK} @ I_{ZK}$		$I_R @ V_R$	
		Nom.(V)	Min.(V)	Max.(V)	Ω	mA	Ω	mA	μA	V
1N5254B	1N5254B	27	25.65	28.35	41	4.6	600	0.25	0.1	21
1N5255B	1N5255B	28	26.6	29.4	44	4.5	600	0.25	0.1	21
1N5256B	1N5256B	30	28.5	31.5	49	4.2	600	0.25	0.1	23
1N5257B	1N5257B	33	31.35	34.65	58	3.8	700	0.25	0.1	25
1N5258B	1N5258B	36	34.2	37.8	70	3.4	700	0.25	0.1	27
1N5259B	1N5259B	39	37.05	40.95	80	3.2	800	0.25	0.1	30
1N5260B	1N5260B	43	40.85	45.15	93	3	900	0.25	0.1	33
1N5261B	1N5261B	47	44.65	49.35	150	2.7	1000	0.25	0.1	36
1N5262B	1N5262B	51	48.45	53.55	125	2.5	1100	0.25	0.1	39
1N5263B	1N5263B	56	53.2	58.8	150	2.2	1300	0.25	0.1	43
1N5264B	1N5264B	60	57	63	170	2.1	1400	0.25	0.1	46
1N5265B	1N5265B	62	58.9	65.1	185	2	1400	0.25	0.1	47
1N5266B	1N5266B	68	64.6	71.4	230	1.8	1600	0.25	0.1	52
1N5267B	1N5267B	75	71.25	78.75	270	1.7	1700	0.25	0.1	56

SUFFIX "B" FOR $\pm 5\%$

CHARACTERISTIC CURVES

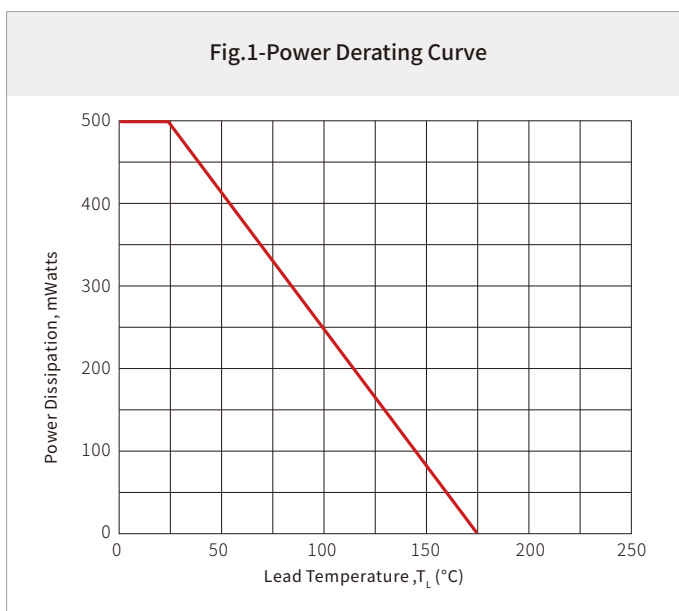
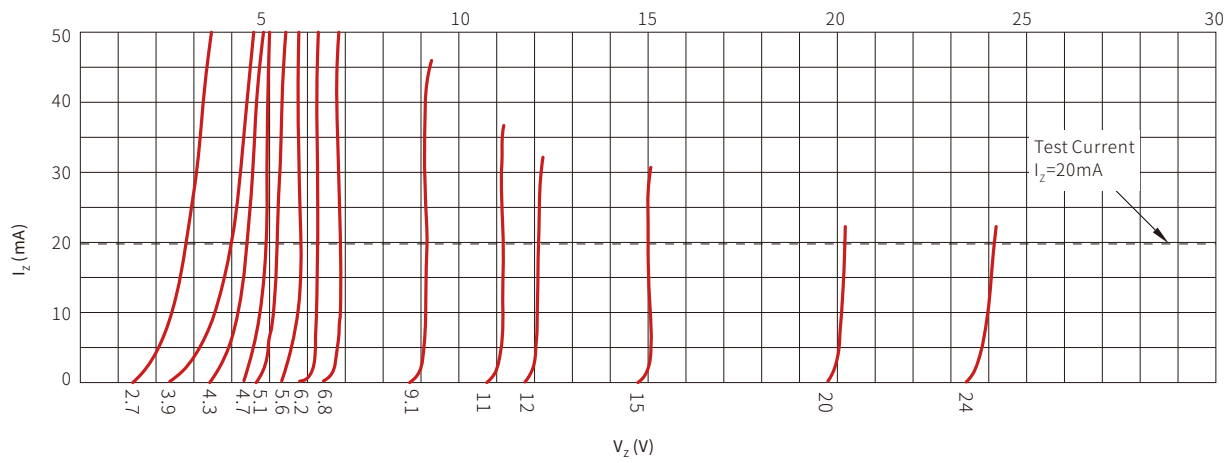
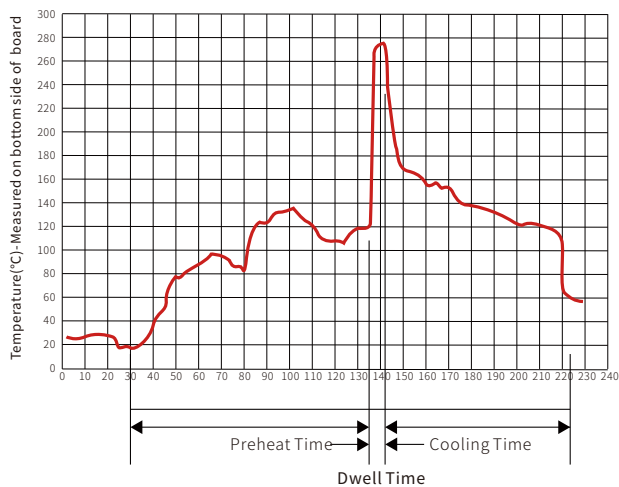


Fig.2-Breakdown Characteristics

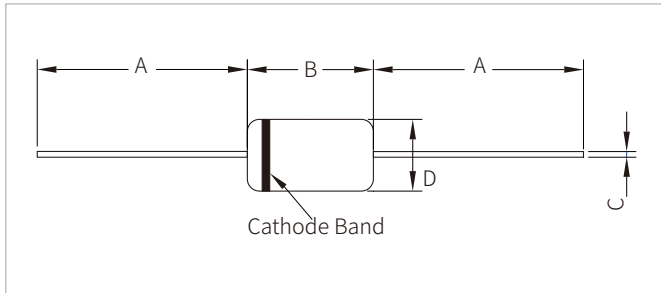


WAVE SOLDERING



Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

DO-35 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	25.40	-	1.00	-
B	-	3.35	-	0.132
C	-	0.43	-	0.017
D	-	1.70	-	0.067

ORDERING INFORMATION

Part Number	Component Package	Per Carton	Description
1N5221B-1N5267B	DO-35	5000pcs	Box

Headquarters

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Pujiang I&E Park
Minhang Shanghai China
201000

Hotline

400-021-5756

Web

<https://www.semiware.com>

Sales Center

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Email: sales18@semiware.com

Customer Service

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Email: sales17@semiware.com

Technical Support

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Email: fae01@semiware.com

Complaint & Suggestions

Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

By QR Code

Website



Wechat

To find your local partner within Semiware's global website: www.semiware.com

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